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Guidance for the Development and Implementation of a Foreign Object Debris (FOD) Control Plan

A White Paper Report Developed by IPC

Association Connecting Electronics Industries

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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Guidance for the Development and Implementation of a Foreign Object Debris (FOD) Control Plan

Developed by the Wire Harness Design Task Group (7-31k)
and IPC-HDBK-620 Handbook Task Group (7-31h) of the
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Users of this publication are encouraged to participate in the development of future revisions.

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